TECHNICAL DATASHEET:
BERGQUIST GAP PAD TGP 3004SF

Known as BERGQUIST GAP PAD 3004SF

PRODUCT DESCRIPTION

High-performance, thermally conductive material with a silicone-free formulation. BERGQUIST GAP PAD TGP 3004SF is a 3.0 W/m·K thermally conductive gap filling material that is silicone-free by design and offers exceptionally low interfacial resistance to adjacent surfaces. It is designed for applications that are silicone-sensitive. The material is constructed using a 0.25 mil PET film that provides a no-tack surface on one side and natural tack on the other: the PET side allows easy disassembly and rework with no residue, while the tacky side allows for ease of handling and placement. Supplied in sheet form or as die-cut parts, with custom thicknesses available upon request.

TYPICAL APPLICATIONS

- Hard disk drives
- HDD / SSD combination drives
- HDD case to tray
- Medical devices
- Optical components and laser optics
- Automotive electronics (HEV, NEV, batteries)
- Solar energy
- LED lighting

PRODUCT FEATURES & BENEFITS

- Thermal conductivity: 3.0 W/m·K
- Excellent thermal performance with exceptionally low interfacial resistance
- Silicone-free formulation for silicone-sensitive applications
- 0.25 mil PET film carrier provides easy disassembly, leaving no residue
- Natural tack on one side allows ease of handling and placement
- UL 94 V-0 flammability rating

PRODUCT SPECIFICATIONS

Technology	Silicone free
Appearance	Light gray
Reinforcement Carrier	0.25 mil PET film
Thickness (ASTM D374)	0.254 to 3.175 mm
Inherent Surface Tack	1 (1 side)
Application	Thermal Management / TIM (Thermal Interface Material)
Operating Temperature Range	-40 to 125°C
Configurations Available	Sheet form; Die-cut parts; Custom thicknesses available upon request
Shelf Life (Optimal Storage)	270 days at 25°C (±3), 50% RH (±10)

Specifications are believed to be accurate at the time of publication and are subject to change without notice. It is the responsibility of the end-user to test and determine suitability of this material for a particular application. H-O will provide samples for this purpose at no charge. **REV. 0**

TYPICAL PROPERTIES OF CURED MATERIAL

Hardness measured at 250 mil thickness, 23°C, bulk rubber, thirty-second delay value.

TECHNICAL DATA	VALUE	UNIT	TEST METHOD / STANDARD
Physical Properties			
Hardness, Shore 00 (30-sec delay, @ 250 mil, 23°C, bulk rubber)	70	—	ASTM D2240
Heat Capacity	0.8	J/g·K	ASTM E1269
Density (bulk rubber)	3.2	g/cc	ASTM D792
Flammability	V-0	—	UL 94
Electrical Properties			
Dielectric Breakdown Voltage	>6,000	VAC	ASTM D149
Dielectric Constant @ 1,000 Hz	8.0	—	ASTM D150
Volume Resistivity	1×10^{11}	ohm·meter	ASTM D257
Thermal Properties			
Thermal Conductivity	3.0	W/(m·K)	ASTM D5470

STORAGE

Store product in the unopened container in a dry location. Optimal storage: 25°C (±3), 50% RH (±10) for a 270-day shelf life. Material removed from containers may be contaminated during use; do not return product to the original container.

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